

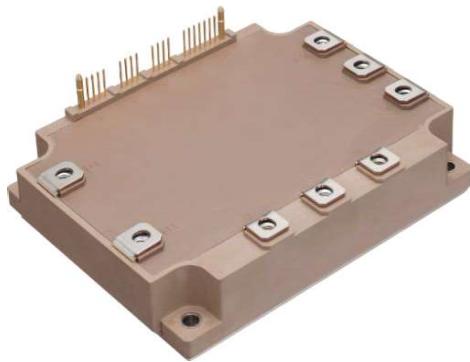
6MBP200XEN065-50

IGBT Modules

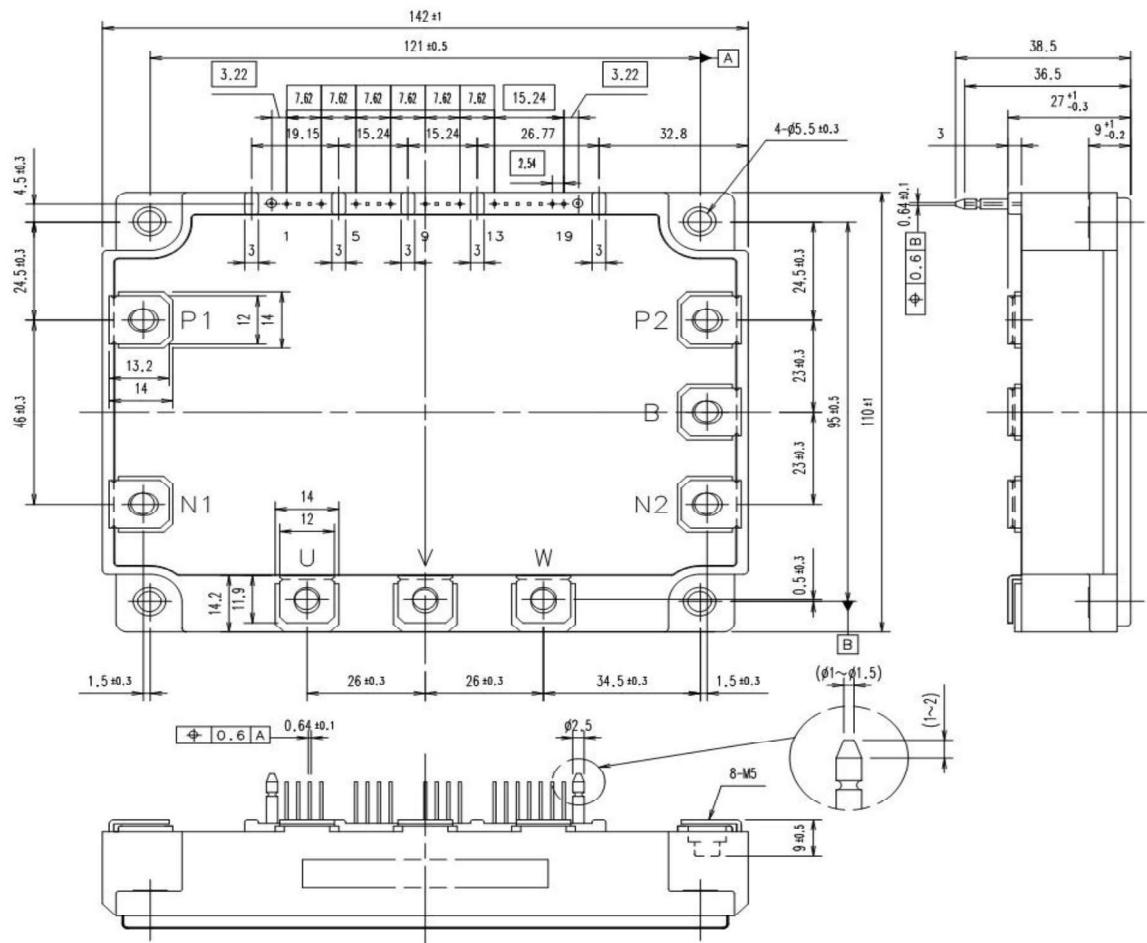
IGBT Module (X series) 650V / 200A / IPM

■ Features

- Temperature protection provided by directly detecting the junction temperature of the IGBTs
 - Low power loss and soft switching
 - High performance and high reliability IGBT with overheating protection
 - Higher reliability because of a big decrease in number of parts in built-in control circuit



■ Outline drawing (Unit : mm)



Weight:940g(typ.)

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IGBT Modules
■ Absolute maximum ratings
 $T_c = 25^\circ\text{C}$, $T_{vj} = 25^\circ\text{C}$, $V_{CC} = 15\text{V}$ unless otherwise specified

	Item	Symbol	Conditions	Min.	Max.	Units
	Collector-Emitter voltage	V_{CES}	*1	-	650	V
	Short circuit voltage	V_{SC}	*2	200	400	V
Inverter	Collector current	I_C	DC	-	200	A
		I_{CP}	1ms	-	400	A
		$-I_C$	Duty=100% *3	-	200	A
	Total power dissipation	P_{tot}	IGBT 1 device *4	-	781	W
Brake	Repetitive peak reverse voltage	V_{RRM}	Diode part	-	-	V
	Collector current	I_C	DC	-	-	A
		I_{CP}	1ms	-	-	A
	Forward current of diode	I_F		-	-	A
	Total power dissipation	P_{tot}	IGBT 1 device *4	-	-	W
	Supply voltage of pre-driver	V_{CC}	*5	-0.5	20	V
	Input signal voltage	V_{in}	*6	-0.5	$V_{CC} + 0.5$	V
	Alarm signal voltage	V_{ALM}	*7	-0.5	V_{CC}	V
	Alarm signal current	I_{ALM}	*8	-	20	mA
	T_{vj} Warning signal voltage	V_{WNG}	*9	-0.5	V_{CC}	V
	T_{vj} Warning signal current	I_{WNG}	*10	-	20	mA
	Virtual junction temperature	T_{vj}		-	175	°C
	Operating virtual junction temperature	T_{vjop}		-	150	°C
	Operating case temperature	T_c		-20	125	°C
	Storage temperature	T_{stg}		-40	125	°C
	Solder temperature	T_{sol}	*11	-	260	°C
	Isolating voltage	V_{isol}	*12	-	2500	Vrms
	Mounting torque of screws to heat sink	M_s	Mounting(M5)	-	3.5	Nm
	Mounting torque of screws to terminals	M_t	Main terminals(M5)	-	3.5	Nm

Notes

*1: V_{CES} shall be applied to the input voltage between all Collector and Emitter】

[P1-(U,V,W), P2-(U,V,W), ((U,V,W,B)-N1.(U,V,W,B)-N2]

*2: In the case of the load inductance to be over 1μH.

*3: Duty=150°C/R_{th(i-c)D}/(I_F×V_F Max.)×100

*4: $P_{tot}=150^\circ\text{C}/R_{th(i-c)Q}$

*5: V_{CC} shall be applied to the input voltage between terminal No.3 and 1, 7 and 5, 11 and 9, 14 and 13.

*6: V_{in} shall be applied to the input voltage between terminal No.2 and 1, 6 and 5, 10 and 9, 16~18 and 13.

*7: V_{ALM} shall be applied to the voltage between terminal No.4 and 1, 8 and 5, 12 and 9, 19 and 13.

*8: I_{ALM} shall be applied to the input current to terminal No.4,8,12 and 19.

*9: V_{WNG} shall be applied to the voltage between terminal No.15 and 13.

*10: I_{WNG} shall be applied to the input current to terminal No.15.

*11: Immersion time 10±1sec. 1 time.

*12: Terminal to base, 50/60Hz sine wave 1 min. All terminals should be connected together during the test.

■ Electrical characteristics
● Main circuit
 $T_{vj} = 25^\circ\text{C}$, $V_{CC} = 15\text{V}$ unless otherwise specified

	Item	Symbol	Conditions	Min.	Typ.	Max.	Units		
Inverter	Collector current at off signal input	I_{CES}	$V_{CE} = 650\text{V}$	-	-	1.0	mA		
	Collector-emitter saturation voltage *13	$V_{CE(\text{sat})}$		$I_C = 200\text{A}$	Terminal	-	1.60	V	
					Chip	-	1.15	V	
Brake	Forward voltage of FWD *13	V_F	$I_F = 200\text{A}$	Terminal	-	2.15	V		
					Chip	-	1.55	V	
	Collector current at off signal input	I_{CES}	$V_{CE} = -V$	-	-	-	mA		
Brake	reverse current	I_{RRM}	$V_R = -V$	-	-	-			
	Collector-emitter saturation voltage *13	$V_{CE(\text{sat})}$	$I_C = -A$	Terminal	-	-	-	V	
					Chip	-	-	V	
Brake	Forward voltage of FWD *13	V_F	$I_F = -A$	Terminal	-	-	-	V	
					Chip	-	-	V	
	Switching time *14				0.5	-	-	μs	
		t_{on}	$I_C = 200\text{A}$ $T_{vj} = 150^\circ\text{C}$ $V_{DC} = 300\text{V}$		0.5	-	-	μs	
		$t_{d(on)}$			0.5	-	-	μs	
		t_{off}			-	-	2.0	μs	
		$t_{d(off)}$			-	-	1.7	μs	
		t_{rr}	$I_F = 200\text{A}$ $T_{vj} = 150^\circ\text{C}$ $V_{DC} = 300\text{V}$		-	-	0.5	μs	
					-	-	-		

*13: The max value is a case where it measures from P2-(U,V,W,B), (U,V,W,B)-N2.

*14: Turn on time (t_{on}) = $t_{d(on)}$ + t_r , Turn off time (t_{off}) = $t_{d(off)}$ + t_f

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● Control circuit

 $T_{vj}=25^{\circ}\text{C}$, $V_{cc}=15\text{V}$ unless otherwise specified

Item	Symbol	Conditions	Min.	Typ.	Max.	Units
Supply current of P-side pre-driver (per one unit)	I_{ccp}	Switching frequency (f_{sw}) = 0~15kHz $T_c = -20 \sim 125^{\circ}\text{C}$	-	-	24	mA
Supply current of N-side pre-driver	I_{ccn}		-	-	75	mA
Input signal threshold voltage	$V_{in(on)}$	V_{in} -GND	ON	1.2	1.4	1.6
	$V_{in(off)}$		OFF	1.5	1.7	1.9
			V	V	V	V

● Protection circuit

 $T_{vj}=25^{\circ}\text{C}$, $V_{cc}=15\text{V}$ unless otherwise specified

Item	Symbol	Conditions	Min.	Typ.	Max.	Units		
Over current protection level	Inverter	$T_{vj}=150^{\circ}\text{C}$	300	-	-	A		
	Brake		-	-	-	A		
Over current protection delay time	t_{dOC}	$T_{vj}=150^{\circ}\text{C}$	-	4.0	-	μs		
Short circuit protection delay time	t_{dSC}	$T_{vj}=150^{\circ}\text{C}$	-	1.0	-	μs		
IGBT chips over heating protection temperature level	T_{jOH}	Surface of IGBT chips	175	-	-	$^{\circ}\text{C}$		
Over heating protection hysteresis	T_{jH}		-	20	-	$^{\circ}\text{C}$		
IGBT chips warning temperature level	T_{jW}	Surface of IGBT chips (Y)	150	-	-			
Warning hysteresis	T_{jWH}		-	10	-			
Under voltage protection level	V_{UV}		11.0	-	12.5	V		
Under voltage protection hysteresis	V_H		0.2	0.5	-	V		
Alarm signal hold time	$t_{ALM(OC)}$	ALM-GND	1.0	2.0	2.4	ms		
	$t_{ALM(UV)}$	$T_c=-20 \sim 125^{\circ}\text{C}$ $V_{cc} \geq 10\text{V}$	3.5	4.0	4.5	ms		
	$t_{ALM(TiOH)}$		7.0	8.0	9.0	ms		
Warning signal hold time	t_{WNG}	WNG-GND $T_c=-20 \sim 125^{\circ}\text{C}$	T_{jw} operating ~ cancellation			ms		
Alarm signal voltage	V_{ALMH}	ALM-GND, without protection			14.5	-	15.0	V
Warning signal voltage	V_{WNGH}	WNG-GND, without warning			14.5	-	15.0	V
Resistance for current limit	R_{ALM}		960	-	1570	Ω		
	R_{WNG}		960	-	1570	Ω		

■ Thermal resistance characteristics ($T_c = 25^{\circ}\text{C}$)

Item	Symbol	Min.	Typ.	Max.	Units
Thermal resistance junction to case *15	Inverter	$R_{th(i-c)Q}$	-	-	0.192 K/W
	FWD	$R_{th(i-c)D}$	-	-	0.277 K/W
	Brake	$R_{th(i-c)Q}$	-	-	K/W
	FWD	$R_{th(i-c)D}$	-	-	K/W
Thermal resistance case to heat sink *16	$R_{th(c-s)}$	-	0.05	-	K/W

*15: For 1 device , the measurement point of the case is just under the chip.

*16: This is the value which is defined mounting on the additional heat sink with 1 W/(m·K) thermal grease.

■ Noise immunity ($V_{dc}=300\text{V}$, $V_{cc}=15\text{V}$)

Item	Conditions	Min.	Typ.	Max.	Units
Common mode rectangular noise	Pulse width 1 μs , polarity \pm , 10min. Judge: no over-current, no miss operating	± 2.0	-	-	kV

■ Recommended operating conditions

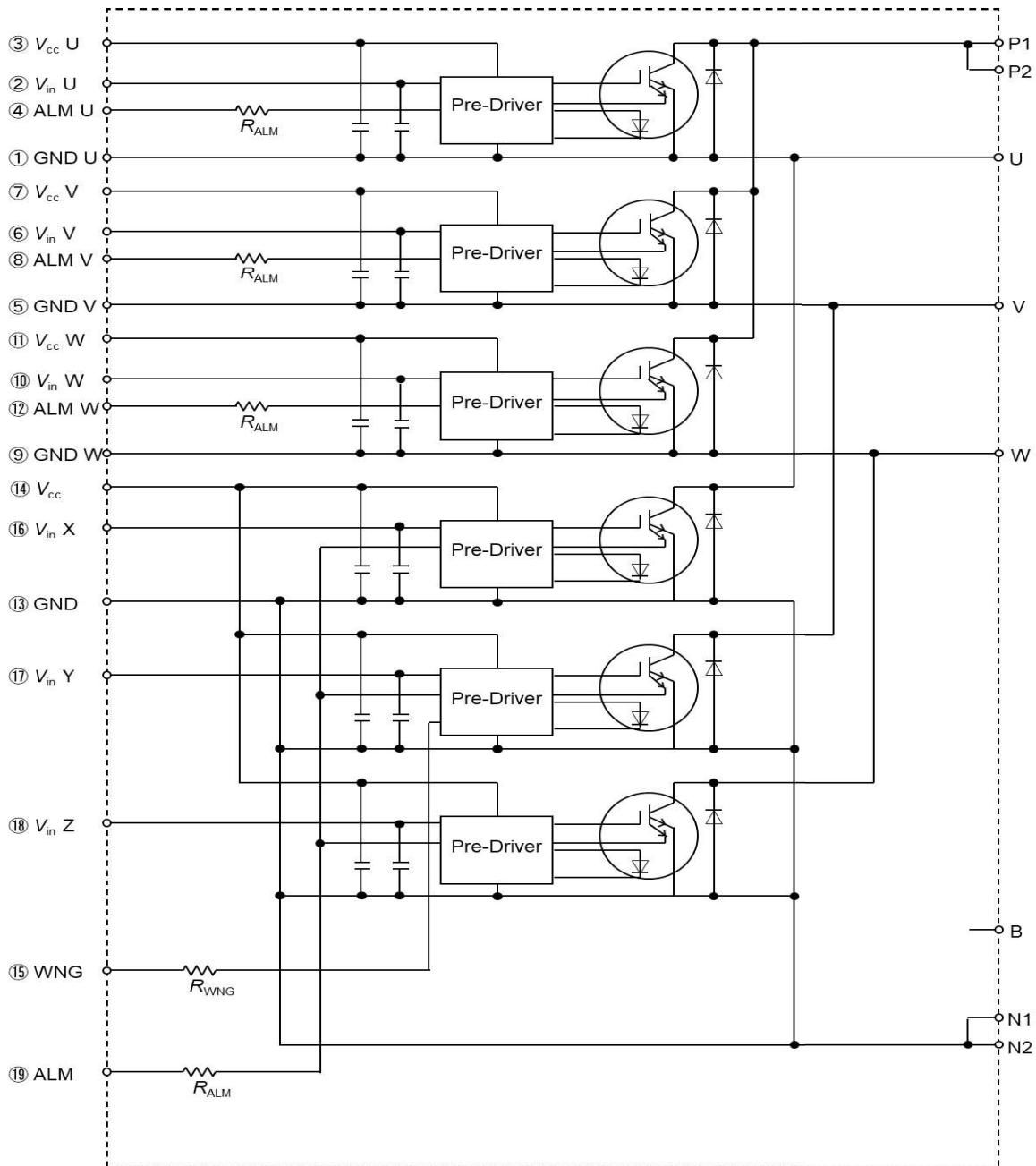
Item	Symbol	Min.	Typ.	Max.	Units
DC bus voltage	V_{dc}	-	-	400	V
Power supply voltage of pre-driver	V_{cc}	13.5	15.0	16.5	V
Switching frequency of IPM	f_{sw}	-	-	20.0	kHz
Arm short through blocking time for IPM's input signal *17	t_{dead}	1.5	-	-	μs
Screw torque (M5)	-	2.5	-	3.5	Nm

*17: $t_{dead} = t_{off} - t_{d(on)}$

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■ Block diagram



Pre-drivers include following functions

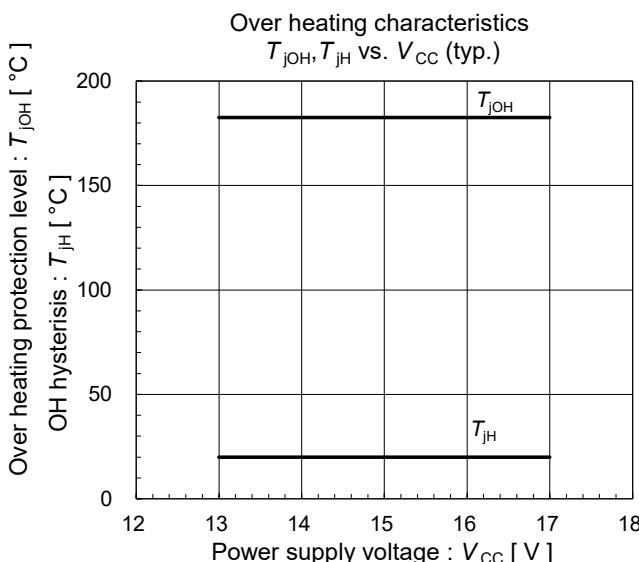
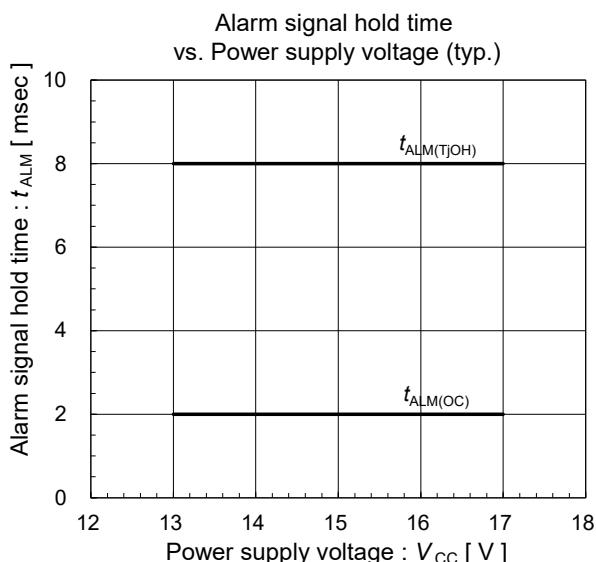
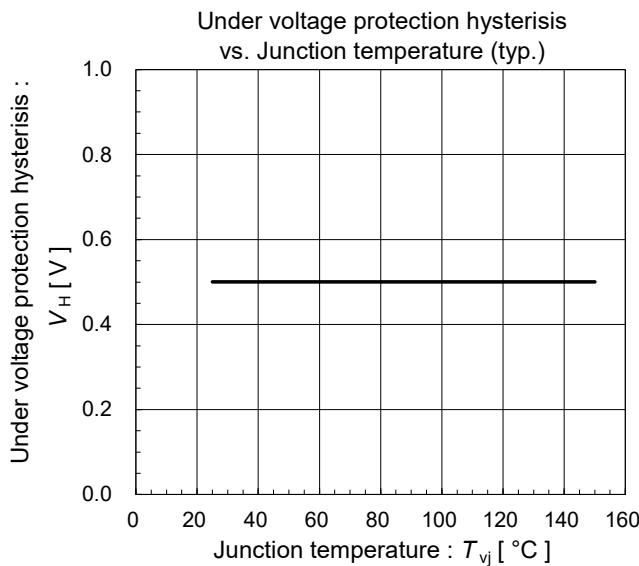
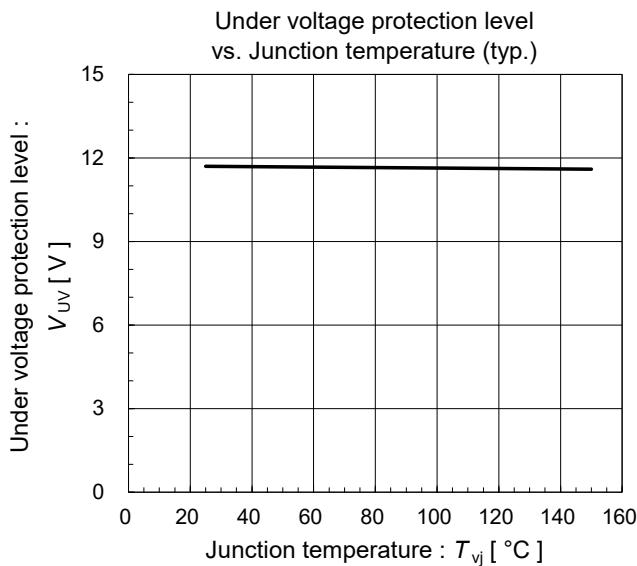
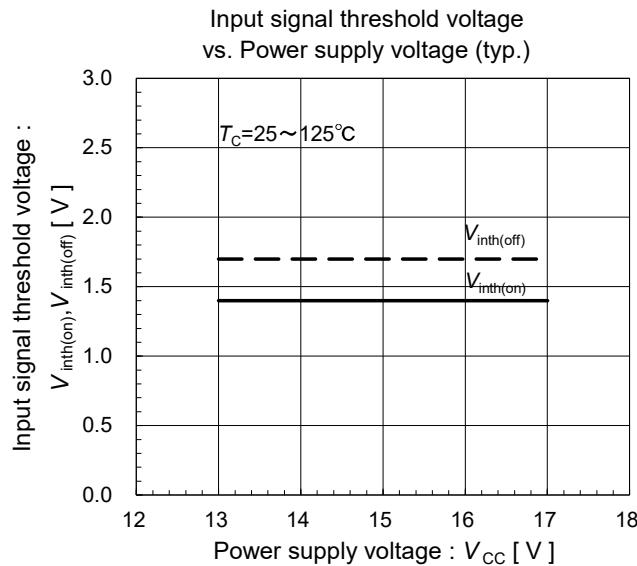
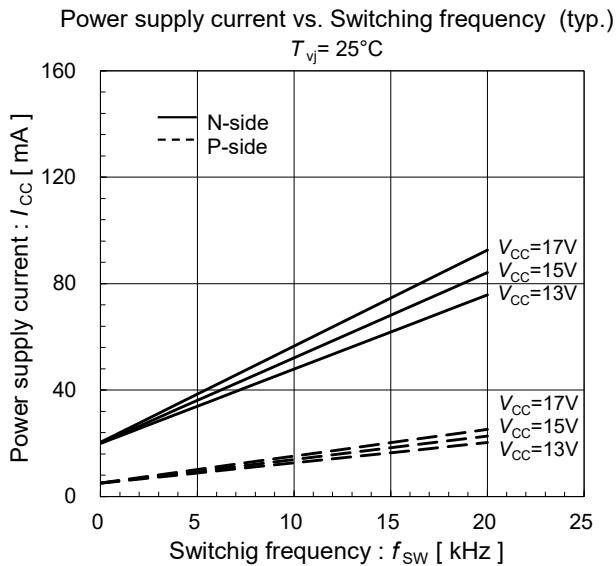
1. Amplifier for driver
2. Short circuit protection
3. Under voltage lockout circuit
4. Over current protection
5. IGBT chip over heating protection

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■ Characteristics (representative)

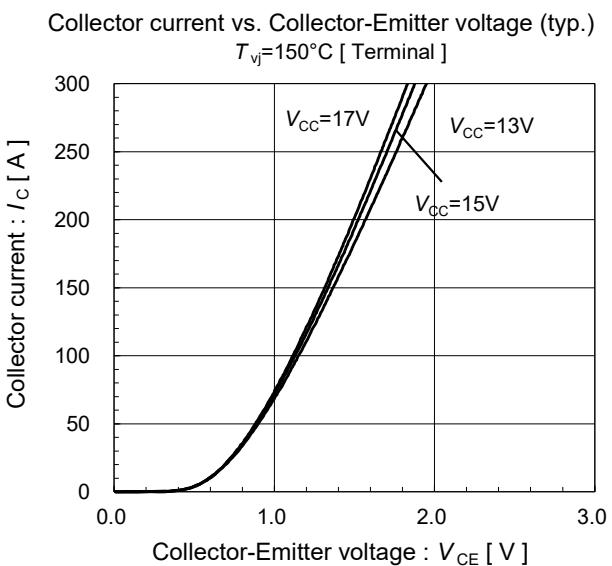
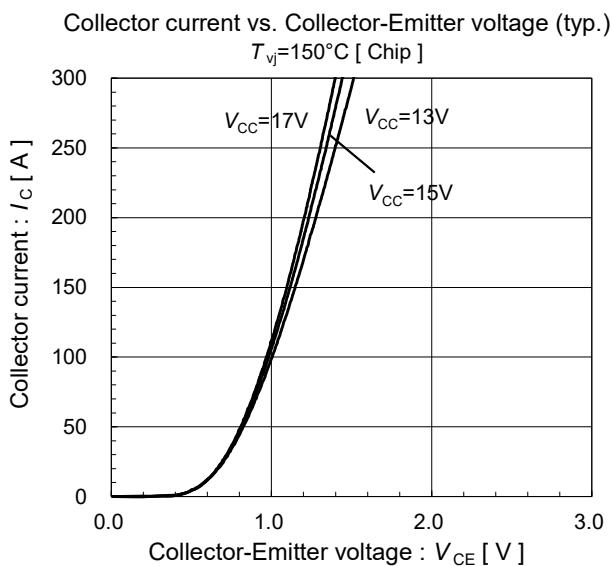
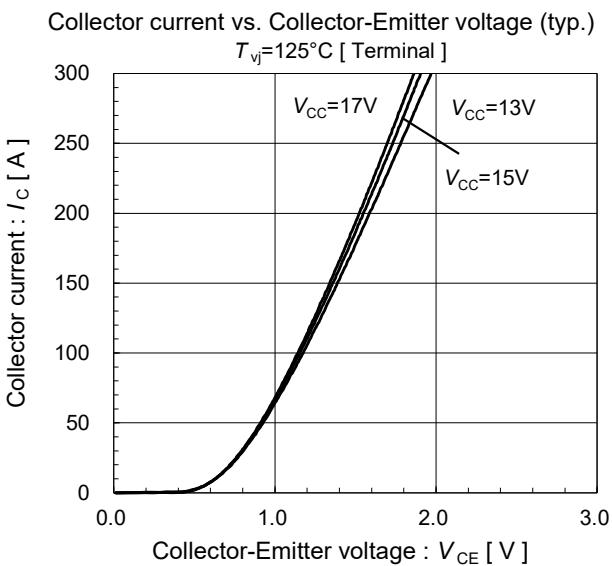
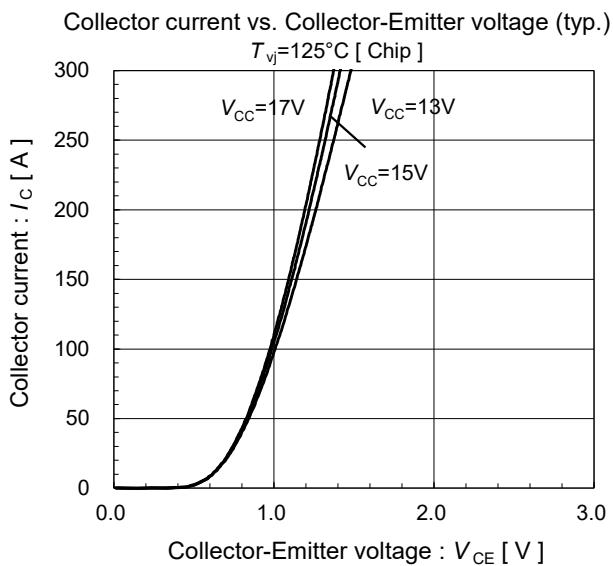
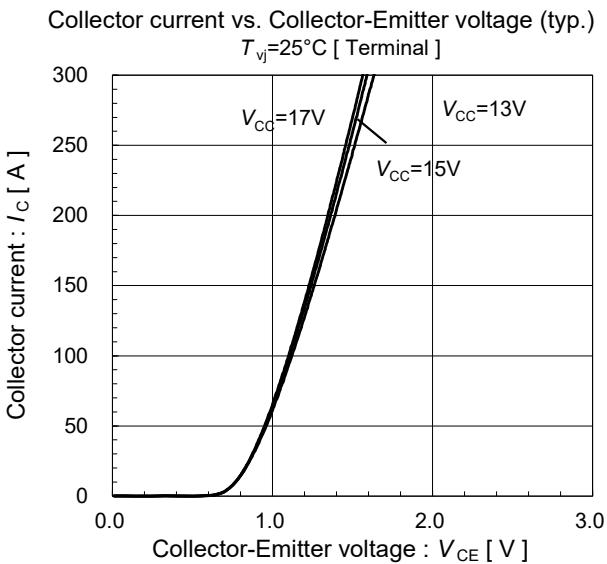
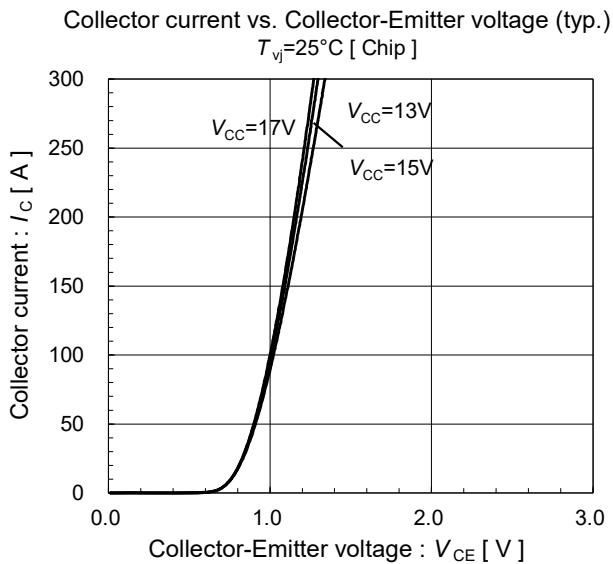
- Control circuit



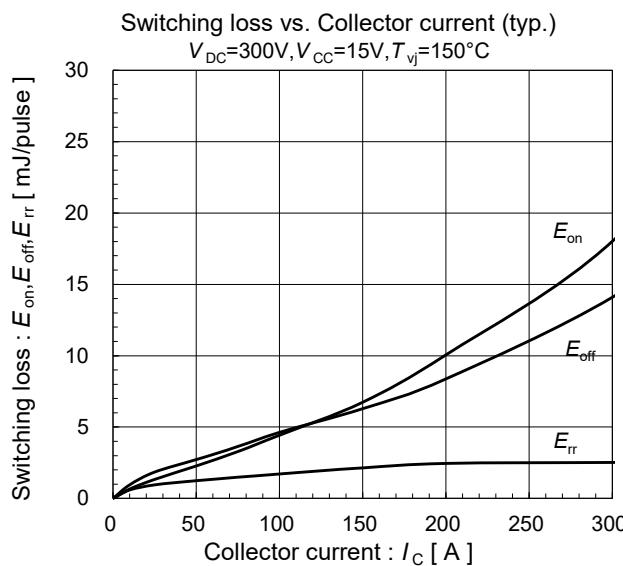
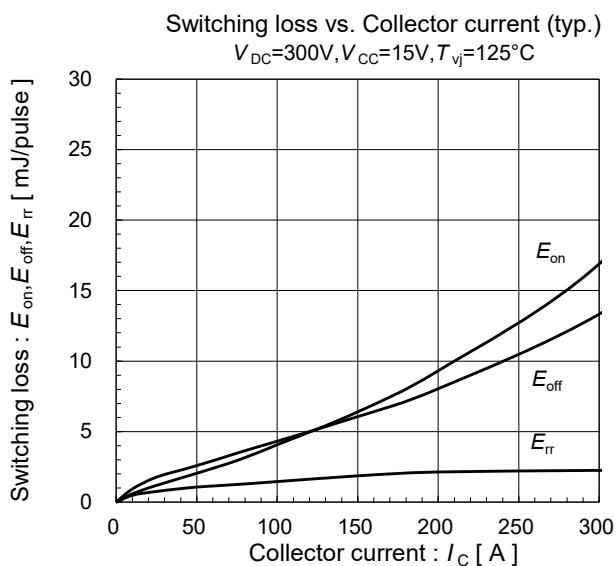
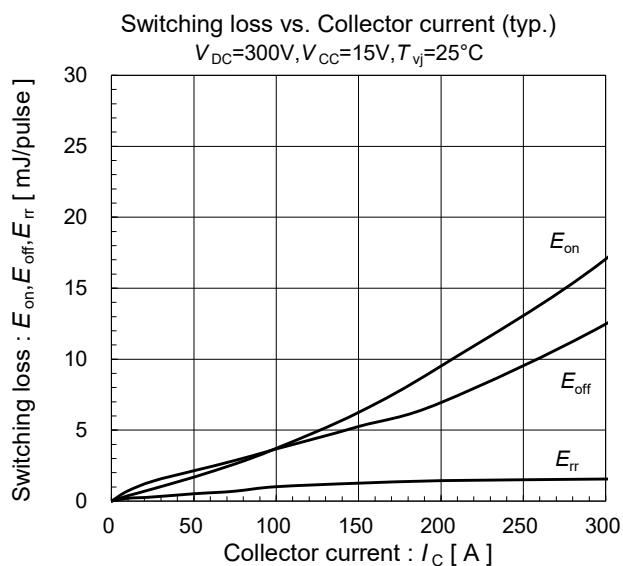
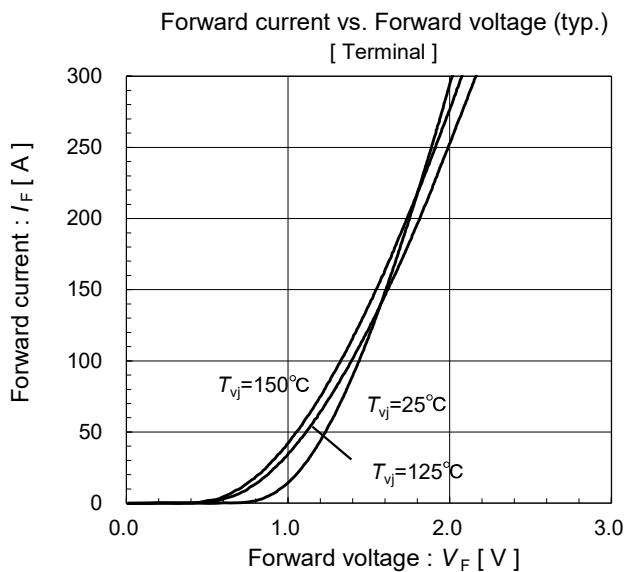
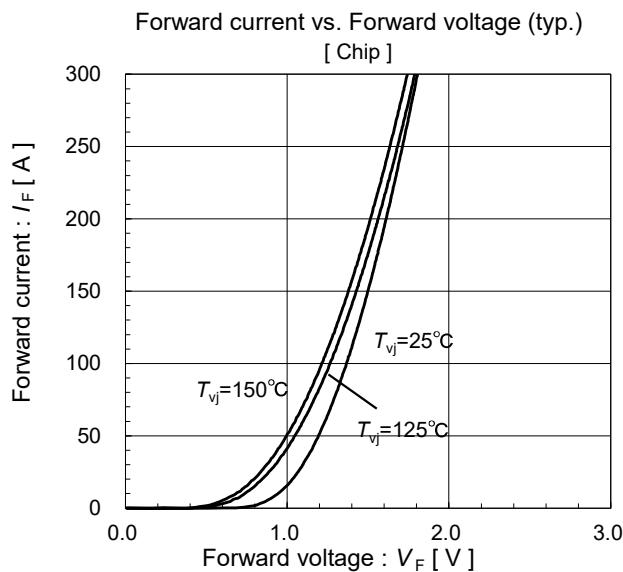
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● Inverter

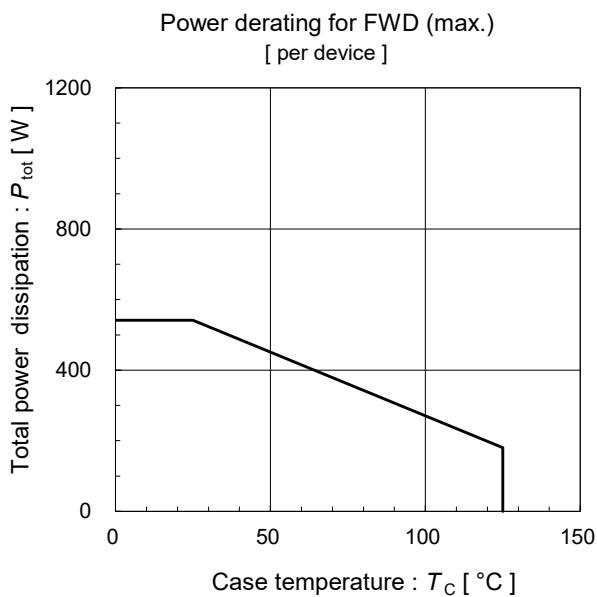
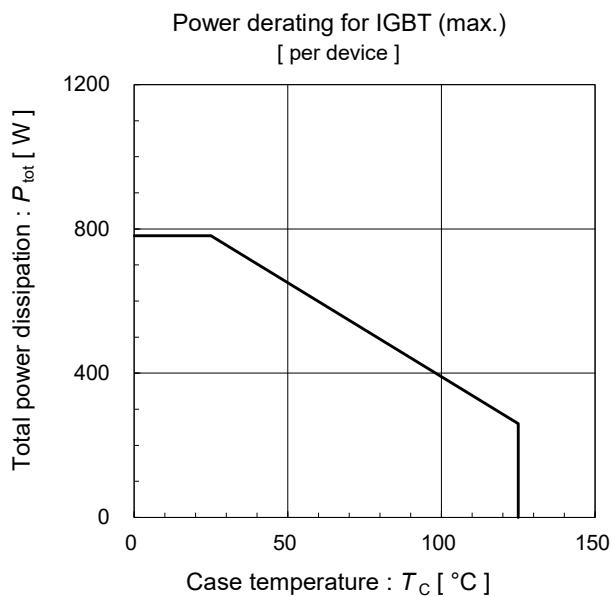
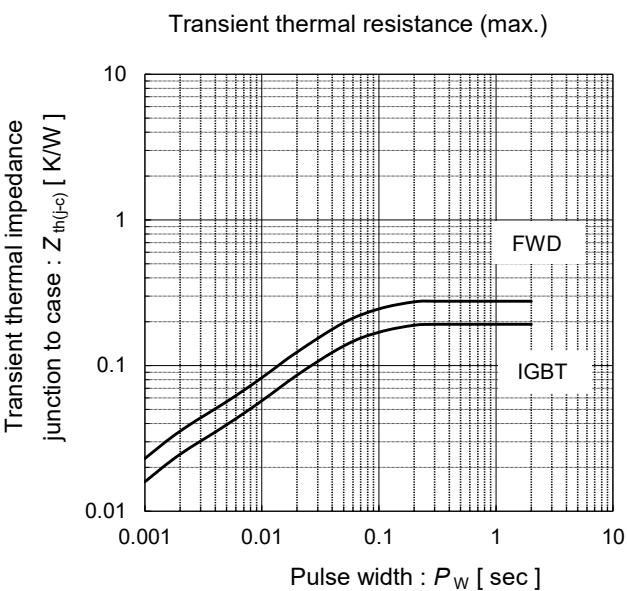
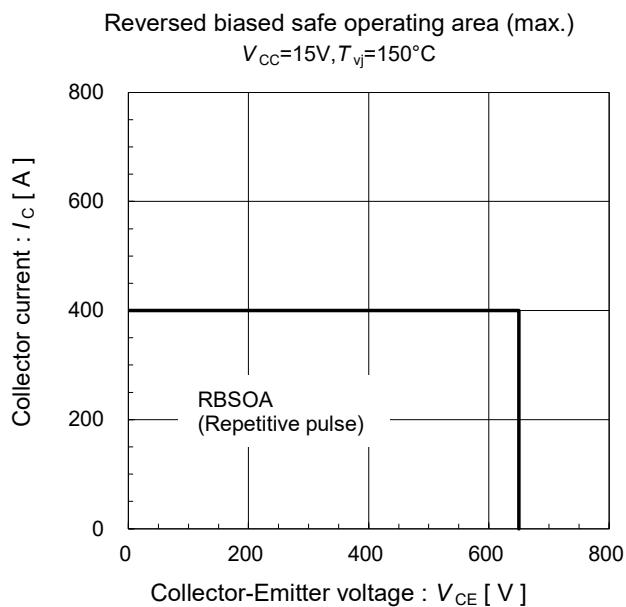


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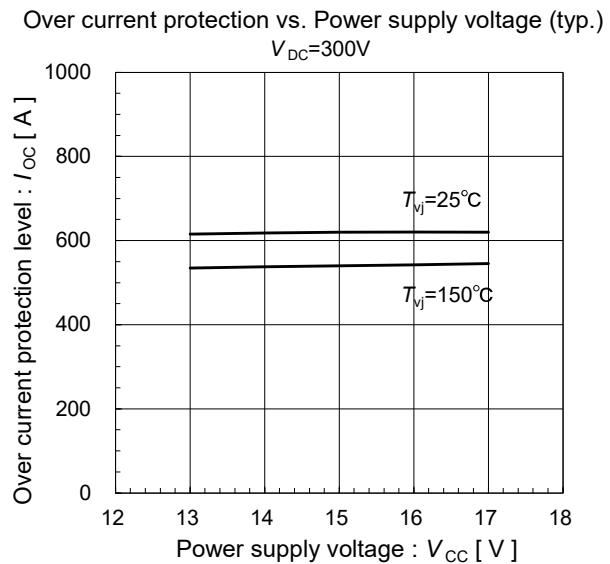
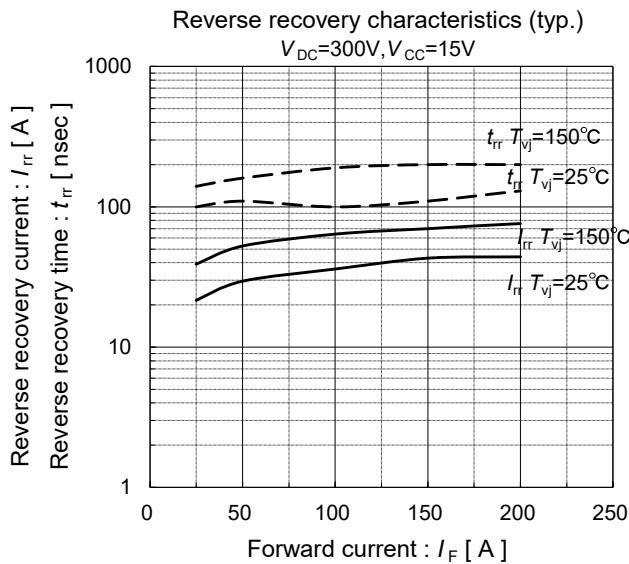
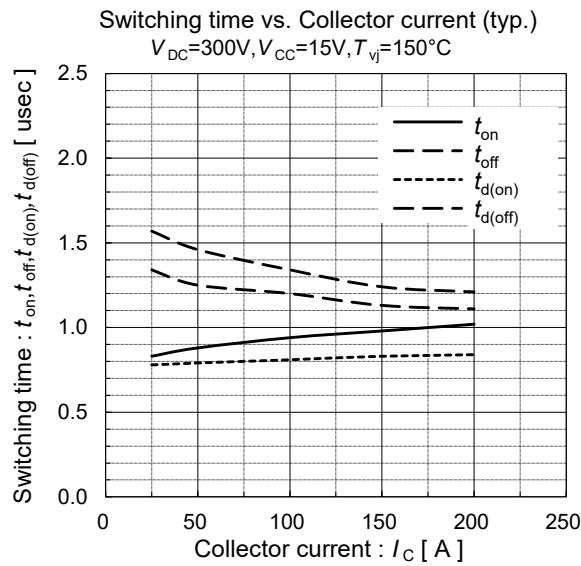
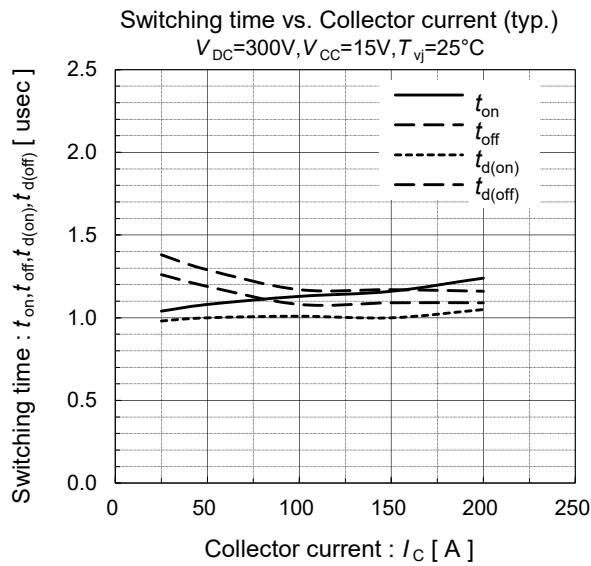
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